

General Description

The AAT7103 25V N-Channel Power MOSFET is a member of AnalogicTech™'s TrenchDMOS™ product family. Using the ultra-high density proprietary TrenchDMOS technology, the product demonstrates high power handling and small size.

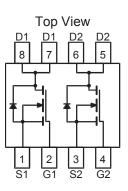
Features

- $V_{DS(MAX)} = 25V$ $I_{D(MAX)}^{(1)} = 6.8 A @ 25^{\circ}C$ Low $R_{DS(ON)}$: 26 m Ω @V_{GS} = 4.5V
 - 41 mΩ @V_{GS} = 2.5V

Applications

- **Battery Packs**
- Cellular & Cordless Telephones
- PDAs, Camcorders, and Cell Phones •

Dual SOP-8 Package



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V _{DS}	Drain-Source Voltage		25	V	
V _{GS}	Gate-Source Voltage		±12		
	Continuous Drain Current @ T _J =150°C ¹	T _A = 25°C	±6.8		
I _D		T _A = 70°C	±5.4	•	
I _{DM}	Pulsed Drain Current 3		±24	A	
I _S	Continuous Source Current (Source-Drain Diode) 1		1.8]	
Р	Maximum Power Dissipation ¹	T _A = 25°C	2.0	W	
P _D		T _A = 70°C	1.25		
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C	

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Thermal Characteristics

Symbol	Description	Value	Units	
$R_{ ext{ heta}JA}$	Typical Junction-to-Ambient steady state, one FET on ²	100	°C/W	
R _{0JA2}	Maximum Junction-to-Ambient Figure, t < 10 sec. ¹ 62.5 °C/W		°C/W	
$R_{ extsf{ heta}JF}$	Typical Junction-to-Foot, one FET on ¹	35	°C/W	



Electrical Characteristics (T_J =25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units	
DC Chara	cteristics	I		1			
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	25			V	
R _{DS(ON)}	Drain-Source ON-Resistance ³	V _{GS} =4.5V, I _D =6.8A		19	26	mΩ	
		V _{GS} =2.5V, I _D =5.4A		28	41		
D(ON)	On-State Drain Current 3	V _{GS} =4.5V ,V _{DS} =5V (Pulsed)	24			A	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=250\mu A$	0.6			V	
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±12V, V _{DS} =0V			±100	nA	
I _{DSS}	Drain Source Leakage Current	V _{GS} =0V, V _{DS} =25V			1	μA	
		V _{GS} =0V, V _{DS} =20V, T _J =70°C			5		
9 _{fs}	Forward Transconductance ³	V _{DS} =5V, I _D =6.8A		20		S	
Dynamic (Characteristics ⁴						
Q_{G}	Total Gate Charge	V _{DS} =15V, R _D =2.2Ω, V _{GS} =4.5V		13	19		
Q _{GS}	Gate-Source Charge	V _{DS} =15V, R _D =2.2Ω, V _{GS} =4.5V		1.9		nC	
Q_{GD}	Gate-Drain Charge	V _{DS} =15V, R _D =2.2Ω, V _{GS} =4.5V		2.9			
t _{D(ON)}	Turn-ON Delay	V_{DD} =15V, V_{GS} =10V, R_{D} =2.2 Ω , RG=6 Ω		15			
t _R	Turn-ON Rise Time	V _{DD} =15V, V _{GS} =10V, R _D =2.2Ω, RG=6Ω		18]	
t _{D(OFF)}	Turn-OFF Delay	V _{DD} =15V, V _{GS} =10V, R _D =2.2Ω, RG=6Ω		36		- ns	
t _F	Turn-OFF Fall Time	V _{DD} =15V, V _{GS} =10V, R _D =2.2Ω, RG=6Ω		27			
Source-Dr	ain Diode Characteristics						
V _{SD}	Source-Drain Forward Voltage ³	V _{GS} =0, I _S =6.8A			1.5	V	
I _S	Continuous Diode Current ¹				1.8	Α	
	•				+	+	

Note 1: Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 10 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in many applications. $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$ where the foot thermal reference is defined as the normal solder mounting surface of the device's leads. $R_{\theta JF}$ is guaranteed by design; however, $R_{\theta FA}$ is determined by PCB design. Actual maximum continuous current is limited by the application's design.

Note 2: Steady state thermal response while mounted on a 1" x 1" PCB with maximum copper area is provided for comparison with other devices. This test condition approximates many battery pack applications.

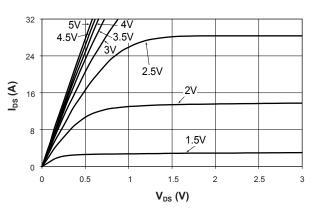
Note 3: Pulsed measurement 300 µs, single pulse.

Note 4: Guaranteed by design. Not subject to production testing.

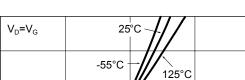


Typical Characteristics

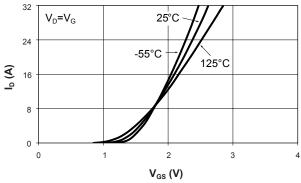
 $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$



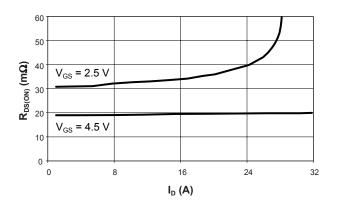
Output Characteristics



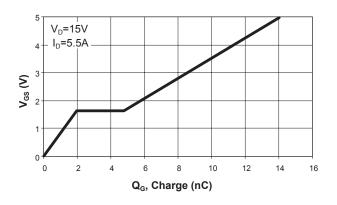
Transfer Characteristics



On-Resistance vs. Drain Current

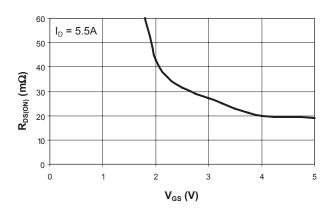


Gate Charge

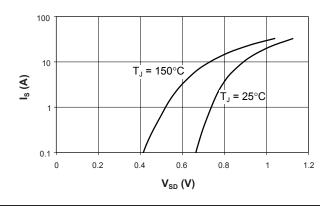


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On-Resistance vs. Gate to Source Voltage



Source-Drain Diode Forward Voltage



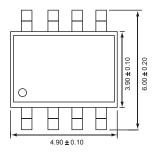


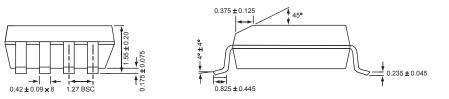
Ordering Information

Package	Marking	Part Number (Tape and Reel)
SOP-8	7103	AAT7103IAS-T1

Note: Sample stock is generally held on all part numbers listed in BOLD.

Package Information





All dimensions in millimeters.

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Advanced Analogic Technologies, Inc. 830 E. Arques Avenue, Sunnyvale, CA 94085 Phone (408) 737-4600 Fax (408) 737-4611

